

POEB1FB

Power over ethernet (PoE)/PD flyback transformer



Product features

- Flyback topology
- IEEE 802.3xx
- Up to 250 kHz switching frequency
- Input range from 32 V to 57 V
- EFD15 SMT package (22.3 mm x 17.3 mm x 9.0 mm)
- 1500 Vac isolation between primary and secondary
- Four power levels: 12, 13, 14 and 18 watts
- Low leakage inductance
- Ferrite core material
- Moisture sensitivity level (MSL): 1

Applications

- Lighting
- Industrial automation
- Security systems
- VoIP phone systems
- Network and Bluetooth access points
- Network routers, repeaters
- Uninterruptible power supplies (UPS)
- Retail point-of-information (POI) systems
- Vending and gaming machines
- Remote cameras

Environmental compliance and general specifications

- Storage temperature (component): -40 °C to +125 °C
- Operating temperature range: -40 °C to +125 °C (ambient plus self-temperature rise)



Product specifications

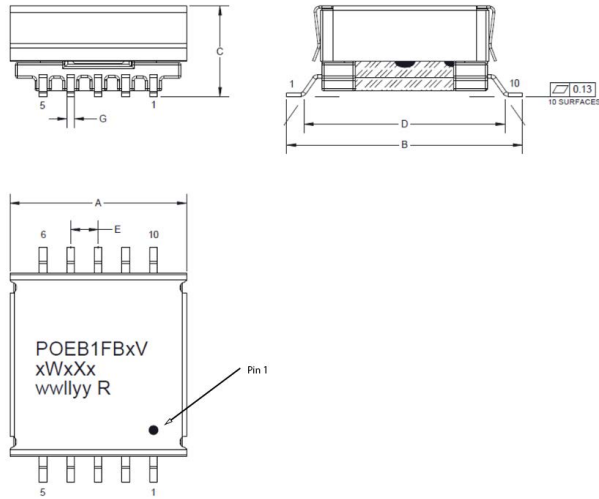
Part number ⁴	Output power (W)	OCL ¹ (μH) ±7%	SCL ² (μH) maximum	I _{sat} ³ (A)	Turns ratio	Output	DCR (mΩ)	DCR (mΩ)	DCR (mΩ)	DCR (mΩ)	Schematic
							maximum @ +25 °C (Pri)	maximum @ +25 °C (Sec 1)	maximum @ +25 °C (Sec 2)	maximum @ +25 °C (Aux)	
POEB1FB1V12W1X12	12	140	1.3	1	1: 0.389: 0.444	(1) x 12.0 V @ 1.0 A	365	40	-	200	1
POEB1FB1V13W2X5	13	155 ± 10%	2.5	1	1: 0.143: 0.143: 0.31	(2) x 5.0 V	500	220	16	270	2
POEB1FB1V14W2D	14	143	1.5	1	1: 0.1: 0.2: 0.25	(1) 5.0 V @ .010 A (1) 9.0 V @ 1.5 A	440	110	28	300	3
POEB1FB1V18W1X12	18	70 ± 10%	1.8	2	1: 0.343: 0.314	(1) x 12.0 V @ 1.5 A	260	30	-	270	4

Turns ratio

Schematic 1: Pri : Sec 1 : Aux
Schematic 2: Pri : Sec 1 :
Sec 2 :Aux
Schematic 3: Pri : Sec 1 Sec
2 : Aux
Schematic 4: Pri : Sec
1 : Aux
±3%

- Open circuit inductance (OCL) is for the primary, test parameters: 100 kHz, 0.1 V_{rms}, 0.0 Adc, +25 °C
- Short circuit inductance (SCL) is for the primary with the other windings shorted, test parameters: 100 kHz, 0.1 V_{rms}, 0.0 Adc, +25 °C
- I_{sat} is for the primary, peak current for less than or equal to 10% rolloff @ +25 °C
- Part Number Definition: POEB1FBxVxWxXx
POEB1FB=Product code and size
xVxW, xV=Version indicator, xW= Output power, xXx=number of outputs and output voltage

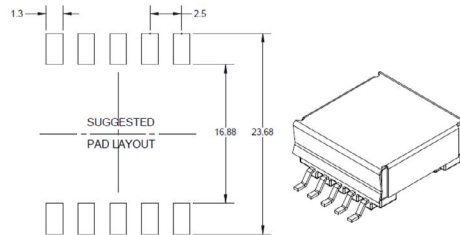
Mechanical parameters, schematic, pad layout (mm)



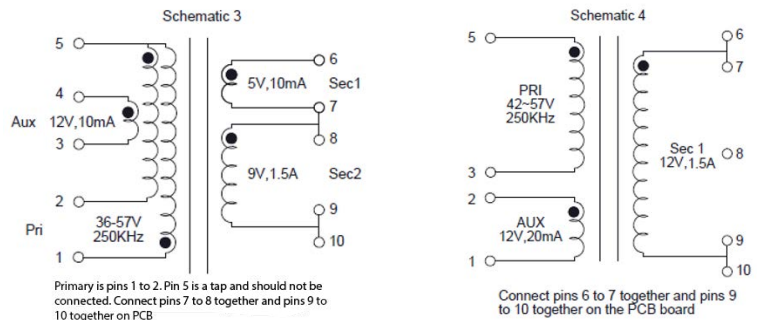
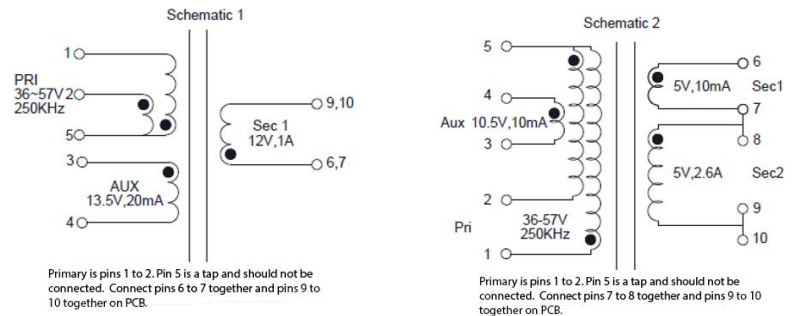
Dimension	Value
A	17.3 maximum
B	22.3 maximum
C	9.0 maximum
D	18.0 typical
E	2.5 ± 0.3
G	0.7 ± 0.15

Part marking: Dot indicates pin 1, POEB1FB = Product code and size,
xV=Version indicator, xW= Output power,
xXx=number of outputs and output voltage.
wwlly R= Lot code
All pin length doesn't include tin icicles
All soldering surfaces to be coplanar within 0.13 millimeters
Tolerances are ±0.25 millimeters unless stated otherwise
Pad layout tolerances are ±0.1 millimeters unless stated otherwise
Traces or vias underneath the transformer is not recommended

Recommended PCB Layout

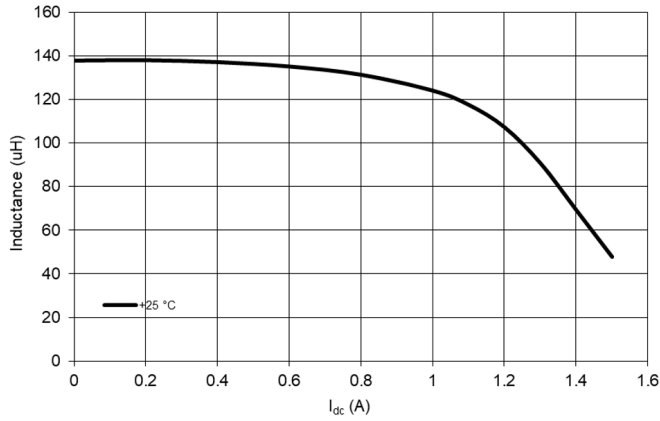


Schematic

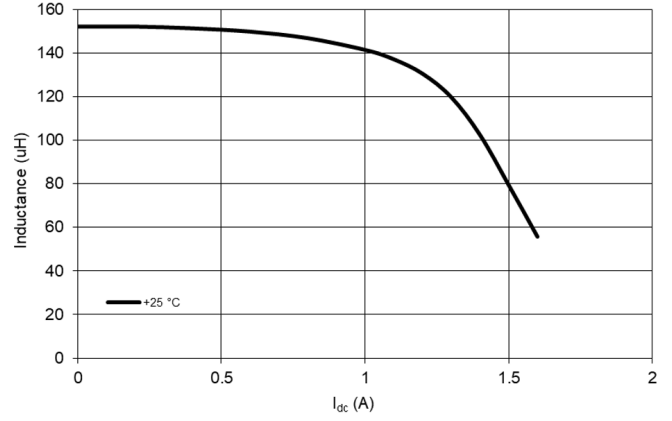


OCL (inductance) vs current characteristics

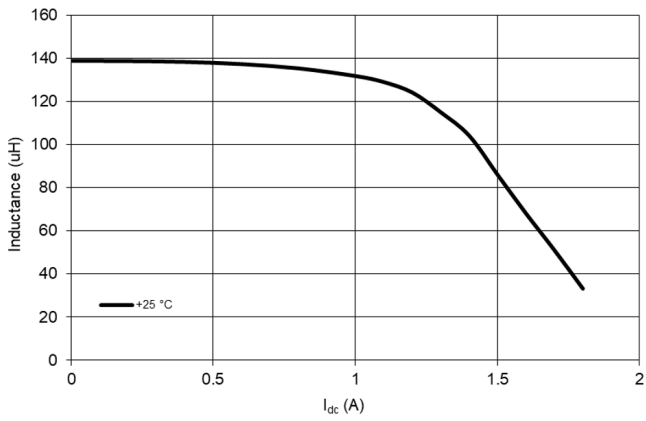
POEB1FB1V12W1X12



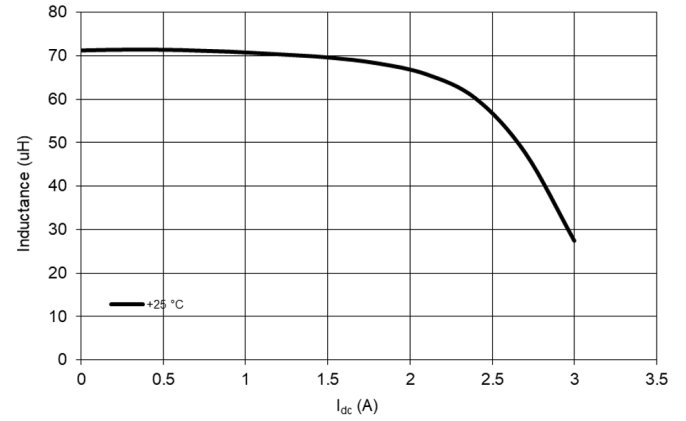
POEB1FB1V13W2X5



POEB1FB1V14W2D

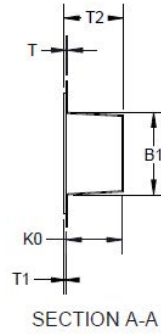
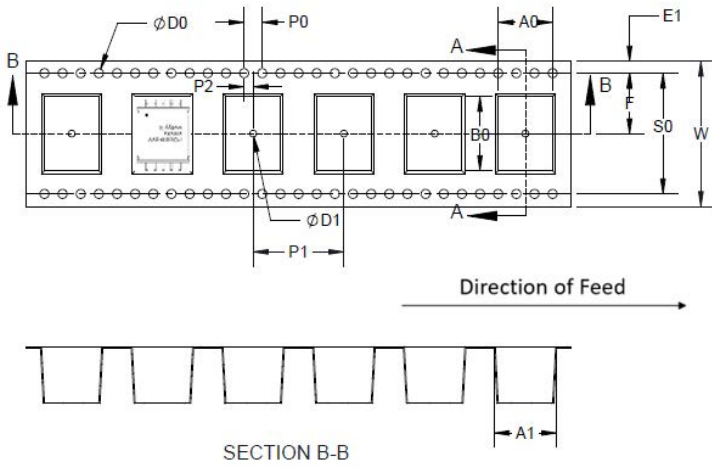


POEB1FB1V18W1X12



Packaging information (mm)

Supplied in tape and reel packaging, 13" diameter reel (EIA-481 compliant)
250 parts per reel



Dimension	Value
$W \pm 0.30$	44
$F \pm 0.15$	20.20
$E1 \pm 0.10$	1.75
$P0 \pm 0.10$	4
$P1 \pm 0.10$	24
$P2 \pm 0.15$	2
$D0 + 0.10/-0$	1.5
D1 minimum	2
$A0 \pm 0.10$	17
A1 ref.	15.4
$B0 \pm 0.10$	23.6
$B1 \pm 0.1$	17.9
$K0 \pm 0.10$	9.5
$T \pm 0.05$	0.5
T1 maximum	0.1
T2 maximum	10.2
S0	40.4

General specifications

Reflow: MIL-STD-202G Condition J, +245 °C ± 5 °C, 30 s ± 5 s, 1 times reflow

Solderability: J-STD-002. 8 hours steam age test, Flux type: ROL0, Solder: +245 °C ± 5 °C

Mechanical shock: MIL-STD-202 Method 213. Half-sine shock pulse, peak=100 g's, 6.0 ms, total 18 shocks

Vibration: MIL-STD-202, Method 204. Gravity= 10 g, Frequency= 10 Hz to 55 Hz to 10 Hz, Direction: 3 (X,Y, Z), each 12 cycles, Duration= 20 minutes in each direction

Salt spray: GB/T6461-2002, Salt spray concentration= 5% ± 1%, Test temperature= +35 ± 2 °C, pH value= 6.5 to 7.2, Time= 48 hours, After removing the product, wash in warm water or salted water, then natural air-dried for 1 hour

High temperature storage test: MIL-STD-202G Method 108, +125 °C, Duration= 1000 hours

Temperature cycling: JESD22 Method JA-104, High temperature= +125 °C, low temperature -40 °C, conversion time 30 minutes, 100 cycles.

Biased humidity: MIL-STD-202G Method 103, +85 °C, 85% RH, Duration= 1000 hours.

Life: MIL-STD-202 Method 108, 1000 hours, +85 °C at rated I_{rms} (Ambient plus self temperature rise no more than +125 °C)

Solder reflow profile

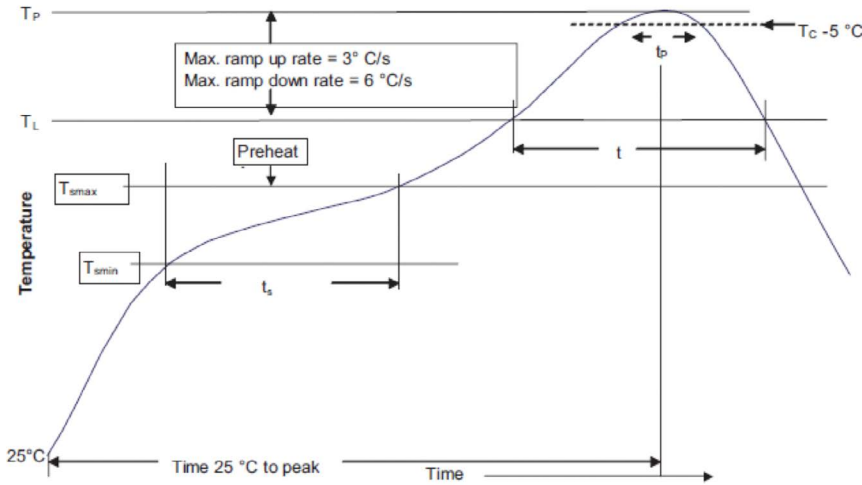


Table 1 - Standard SnPb solder (T_C)

Package thickness	Volume mm^3 <350	Volume mm^3 \geq 350
<2.5 mm)	235 °C	220 °C
\geq 2.5 mm	220 °C	220 °C

Table 2 - Lead (Pb) free solder (T_C)

Package thickness	Volume mm^3 <350	Volume mm^3 350 - 2000	Volume mm^3 >2000
<1.6 mm	260 °C	260 °C	260 °C
1.6 – 2.5 mm	260 °C	250 °C	245 °C
>2.5 mm	250 °C	245 °C	245 °C

Profile feature	Standard SnPb solder	Lead (Pb) free solder
Preheat and soak		
• Temperature min. (T_{smin})	100 °C	150 °C
• Temperature max. (T_{smax})	150 °C	200 °C
• Time (T_{smin} to T_{smax}) (t_s)	60-120 seconds	60-120 seconds
Ramp up rate T_L to T_p	3 °C/ second max.	3 °C/ second max.
Liquidous temperature (T_L)	183 °C	217 °C
Time (t_L) maintained above T_L	60-150 seconds	60-150 seconds
Peak package body temperature (T_p)*	Table 1	Table 2
Time (t_p)* within 5 °C of the specified classification temperature (T_C)	10 seconds*	10 seconds*
Ramp-down rate (T_p to T_L)	6 °C/ second max.	6 °C/ second max.
Time 25 °C to peak temperature	6 minutes max.	8 minutes max.

* Tolerance for peak profile temperature (T_p) is defined as a supplier minimum and a user maximum.

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